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Part Number: [170382-0001](#)
Status: **Active**
Overview: ZXP® Modular I/O Interconnect System
Description: ZXP® zSFP+™ Right Angle, SMT, 20 Circuits, 0.38µm Gold (Au), Tin Tails

Documents:

[3D Model](#) [Test Summary TS-170382-0002 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

UL E29179

General

Product Family I/O Connectors
 Series [170382](#)
 Application Module-to-Board
 Component Type I/O Plug Connector Subassembly
 Overview [ZXP® Modular I/O Interconnect System](#)
 Product Name ZXP® zSFP+™
 Type N/A
 UPC 884982557260

Physical

Boot Color N/A
 Circuits (Loaded) 20
 Circuits (maximum) 20
 Color - Resin 0.5A
 Durability (mating cycles max) 100
 Flammability 94V-0
 Gender Female
 Keying to Mating Part None
 Lock to Mating Part No
 Material - Metal Brass, Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic, Polycarbonate
 Net Weight 0.857/g
 Number of Rows 2
 Orientation Right Angle
 PC Tail Length 2.07mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness - Recommended 1.57mm
 Packaging Type Reel
 Panel Mount No
 Pitch - Mating Interface 0.80mm
 Pitch - Termination Interface 0.80mm
 Plating min - Mating 0.381µm
 Plating min - Termination 0.381µm
 Polarized to Mating Part Yes
 Polarized to PCB Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -40°C to +85°C
 Termination Interface: Style Surface Mount
 Waterproof / Dustproof No

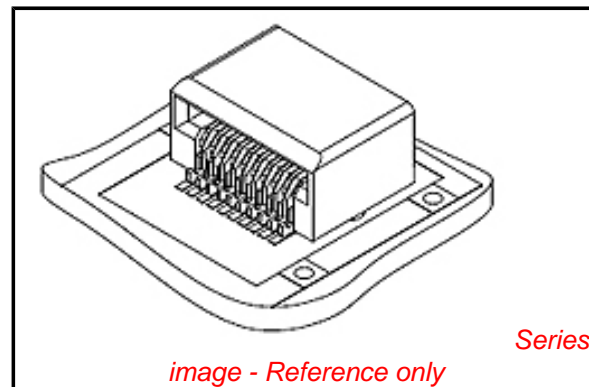


image - Reference only

EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Contains SVHC: No**
**Low-Halogen Status
 Low-Halogen**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of
 Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
 non-product compliance questions.

Search Parts in this Series

170382Series

Electrical

Current - Maximum per Contact	0.5A
Grounding to Panel	None
Voltage - Maximum	120V AC (RMS)/DC

Solder Process Data

Duration at Max. Process Temperature (seconds)	15
Lead-free Process Capability	Reflow Capable (SMT only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Electrical Model Document	EE-170382-0001
S-Parameter Model	SP-170382-0001
Sales Drawing	SD-170382-001
Signal Integrity Report	SI-170382-0001
Test Summary	TS-170382-0002

This document was generated on 01/21/2013

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